LAN A AUUTOO T AteNear Data Processing PERSPECTIVE

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Agenda

The Challenge : "Memory Wall"/Von Neumann Bottleneck

Traditional Solutions

New Technology Opportunities – 3D Stacking, NVM, MCP (Xeon+FPGA)

Programming Model for Near Data Processing

Example Applications – HPC Simulation using GANs/DL

Summary / Call-to-Action

The Memory Wall

Core count doubling \sim every 2 years DRAM DIMM capacity doubling \sim every 3 years

Source: Lim et al., ISCA 2009.

The Memory Wall (contd.)

 \triangle Capacity \triangle Latency (tRC)

Von Neumann Bottleneck

The term "Von Neumann bottleneck" was coined by John Backus in his 1977 ACM Turing Award lecture.

According to Backus:

"Surely there must be a less primitive way of making big changes in the store than by pushing vast numbers of words back and forth through the Von Neumann bottleneck. Not only is this tube a literal bottleneck for the data traffic of a problem, but, more importantly, it is an intellectual bottleneck that has kept us tied to word-at-a-time thinking instead of encouraging us to think in terms of the larger conceptual units of the task at hand. Thus programming is basically planning and detailing the enormous traffic of words through the Von Neumann bottleneck, and much of that traffic concerns not significant data itself, but where to find it."

The Challenge

Conventional computing architecture is CPU-centric

– All data is moved to/from memory for computation

The "Memory Wall" (aka Von Neumann bottleneck)

- Latency/Bandwidth \rightarrow Perf.; Mitigations expensive
- Data movement \rightarrow Energy; Significant

Traditional approach: *Memory in Processor*

- Registers, cache hierarchy, dedicated buffers
- Reduce data movement by caching and re-use

Memory Wall : *Performance*

Latency

- Ever larger, deeper caches
- uArch (Spec., OOO, HT, ...)
- Data prefetching (sw/hw)
- Fast (optical?) interconnect
- …

Bandwidth

More memory controllers

3d-DRAM stacking

More/Faster mem. channels

Traditional approaches to scaling the "memory wall" are expen\$ive

\rightarrow Die\$\$\$

- \rightarrow Die \$\$, Complexity(TTM)
- \rightarrow Application dependent
- \rightarrow Tech \$\$, E-O-E overhead

- \rightarrow Die\$, Complexity(TTM)
- \rightarrow Pin\$\$, Power, Elec(TTM)

Memory Wall : *Energy*

Energy/Byte :: Energy/Operation == 1 :: 3

Nominally, an operation needs upto 24 bytes (3.17 nJ/Op)

Caching+reuse reduces data movement energy $(\rightarrow$ -1.2 nJ/Op)

Data movement across the memory wall limits performance and is energy expensive!

Emerging Tech Opportunities

eDRAM

- **Logic compatible memory tech**
- High BW Memory Cache
- On-die or Multi-chip Pkg
- Reduces nJ/Byte by $-5x$

3D Stacked Memory (HBM/HMC)

- Low power/High BW interface
- Stacked memory w/ logic buffer
- Higher density DRAM arrays

A new level in the memory hierarchy that combines logic + memory

The NDP Spectrum

Execute arith & address ops near memory sub-system to:

- Reduce data movement costs (\blacklozenge energy, \blacklozenge performance)
- Enable wide parallel operations (exploit memory BW)
- Complement, even improve, caching

NDP Primitives

Case Study: Gather/Scatter CiM

Gather/Scatter CiM improves cache locality through optimized data movements

Case Study: Stream Filter CiM

intel.

NVME revolution

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Ruler SSD Form Factor Project

Objectives FLASH TCO: Understand the TCO and engineer to exploit it

- 3D NAND economics are enabling the tipping point. *How can we accelerate this?*
- Avoid the limitations of classical SFF solutions
- Enable scale: Desired a form factor that will support *Very High* system performance
	- *1PB per Rack U* was our stake in the ground objective
	- Now you can buy leading edge HPC bandwidth/IOPS
- Enable dynamic range: Desired a form factor that can efficiently service a wide range of system configurations and performance points
	- Cover the needs of both *Scale Up* and *Scale Out* platforms
	- Support wide range of configurations from modest to high performance
- Attack system cost/complexity points
	- Learn from legacy form factor experience

Front Loading, Hot Swappable, Ruler SSD (RSSD)
RSSDs ar[e](http://www.google.com/url?sa=i&rct=j&q=&esrc=s&source=images&cd=&cad=rja&uact=8&ved=0ahUKEwiAkpOx9MPLAhVX7mMKHfu4ANYQjRwIBw&url=http://www.woodrowrulers.com/products/rulers/metric/12-brassmaple-ruler-with-an-inch-scale/&psig=AFQjCNFUIUScsz80-ECZaYDFhuZFGQAH8A&ust=1458173083609024) optimized for high density 1U storage

- Modules are 38.6mm tall and packed at a 12.5mm pitch
- RSSDs are front loading and hot swappable
- RSSDs natively incorporate LEDs and a latching mechanism

1U JBOD

Allows Provisioning Compute Resources to the Application's Needs

NVMe OVER fabric

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NVMe* over Fabrics

Host and Target Stack Status

Linux* Host and Target Kernel drivers operational

- Target configured with NVMe* PCIe* SSD ×
- To ensure fabrics transport is fabric agnostic it has been tested on InfiniBand*, iWARP, RoCE RDMA adapters ٠
- Host has been tested with multiple target implementations п
- Included in upstream kernel since 4.5; 4.8.4 has the latest changes r

NVMe-over-OPA status:

- Compliant with NVMeOF specs 1.0 ×
- OPA driver implemented specs in 10.2 driver release
- NVMe-over-OPA qualification and support at Q4'16 ×
- Presented at SC16 by EchoStreams, RSC Group and others. ×

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3D Xpoint™ Technology

3d XPOINT

Scalable

Material Advances

Why 3D XPoint™ NVM in SSD and DIMM?

Apache Pass (AEP)

(For the Purley 2S+ platform in 2018)

1. Highest performance

- Bandwidth, latency, IOPS
- 2. Highest endurance

3. System memory

- DRAM replacement
- Persistent memory

4. Diskless platform

• Soft RAID and disk image boot

Data granularity: 64B cacheline

Coldstream

(For platforms supporting PCIe from 2016)

1. Serviceability

- PCIe standard interface
- Hot add / remove
- Hardware or software RAID support
- 2. Higher capacity (vs. AEP)
	- Up to 3 TB per drive
- 3. Lower \$/GB (vs. AEP)
- 4. Higher endurance & performance (vs. NAND)
	- NAND / HDD upgrade or replacement

Data granularity: 512B/4KB block

Apache Pass Overview

(3D XPoint™ based Memory Module for the Data Center)

* DIMM population shown as an example only.

DAOS – OPEN SOURCE DISTRIBUTED OBJECTS

Distributed **A**synchronous **O**bject **S**torage

Lightweight Storage Stack

Ultra-fine grained I/O

New Storage Model

Extreme Scale-out & Resilience

Multi-Tier

New Workflow Methodologies

Open source - APACHE 2.0 License

intel)

Disruptive Technology

Disruptive Technology

slower faster

Lightweight Storage Stack

End-to-end OS bypass

Mercury userspace function shipping

- **MPI equivalent communications latency**
- Built over libfabric

Applications link directly with DAOS lib

- Direct call, no context switch
- No locking, caching or data copy

Userspace DAOS server

- Mmap non-volatile memory (NVML)
- NVMe access through SPDK*
- **User-level thread with Argobots****

Ultra-fine grained I/O

Mix of storage technologies

NVRAM (3D XPoint™ NVDIMMs)

- DAOS metadata & application metadata
- **Byte-granular application data**

NVMe (NAND, 3D NAND, 3D XPoint™)

- Cheaper storage for bulk data
- Multi-KB

I/Os are logged & inserted into persistent index All I/O operations tagged/indexed by version Non-destructive write: log blob@version Consistent read: blob@version No alignment constraints

New Storage Model

Storage Pool

Reservation of distributed storage within a tier

Integration with resource manager

Container

Aggregate related datasets into manageable entity

Distributed across entire storage pool

Unit of snapshot/transaction

Object

- Collection of related arrays/values with own distribution/resilience schema
- Key-value store with flexible multi-level key
	- fine-grain control over colocation of related data

Record

• Arbitrary binary blob from single byte to several **Mbytes**

Extreme Scale-out & Resilience

Scalable communications

- Track jobs and not individual nodes
- Tree-based communication
- Scalable I/O
- Lockless, no read-modify-write
- Ad hoc concurrency control mechanism
- Shared-nothing distribution & redundancy schema
- Algorithmic & progressive layout
- Replication/erasure code with declustered placement

Storage system failure

- Failed target(s) evicted
- Automated online rebuild & rebalancing End-to-end integrity

Hash (object.Dkey)

• Checksums can be provided by I/O middleware

Fault domain separation

- Stored and verified on read & scrubbing Application failure
- Scalable distributed transaction exported to I/O middleware
- Automated recovery to roll back uncommitted changes

Hash (object.Dk

DAOS Deployment

DAOS Ecosystem

Energy constrains our platform perf – top to bottom

Data movement consumes much of that energy

CiM saves energy and improves performance by optimizing & reducing data movement

Upcoming memory transitions present a great opportunity to exploit CiM

Call-to-Action

- Choose key workloads in segments to drive definition
- Define ISA extensions & platform architecture
- **Address multisocket/distributed memory challenges**
- **Implement performance libraries using CiM primitives**
- Prototype platforms for implementation tradeoffs

Develop HW/SW deployment & enabling strategy

